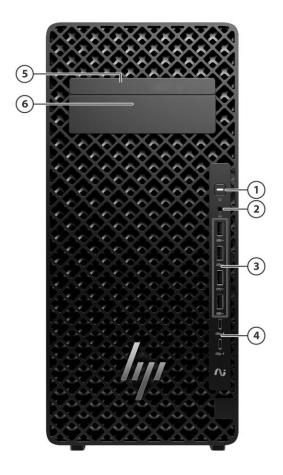
Overview

HP Z2 Tower G1i Workstation

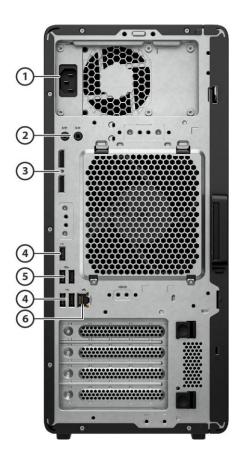


front

- 1. Power button
- 2. headphone/microphone combo
- 3. 4 SuperSpeed USB Std-A 10Gbps ports
- 4. 2 SuperSpeed USB-C® 20Gbps port (charge supports up to 5V/3A)
- 5. Slim ODD bay (Optional)
- 6. External 3.5" bay



Overview



- 1. Power connector
- 1 Audio Line-in jack
 1 Audio Line-out jack
- 3. 2 DisplayPort 1.4 ports

rear

- 4. 3 Hi-Speed USB Std-A 480Mbps ports
- 5. 2 SuperSpeed USB Std-A 10Gbps ports
- 6. 1 1Gb LAN



Overview

Operating Systems

Preinstalled:

- Windows 11 Pro 64¹
- Windows 11 Home 64¹
- Linux®-ready⁴
- Ubuntu[®] 24.04 LTS^{2,3}

Supported:

- Windows 10
- Red Hat® Enterprise Linux® Workstation 9⁴
- SUSE Linux® Enterprise Desktop 15⁴

http://www.hp.com/support/linux_hardware_matrix

Ubuntu[®] 24.04 LTS^{2,3}

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 11 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

² Not all features are available in all editions or versions of Ubuntu[®]. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requires may apply over time for updates.

³ A certified preloaded version of Ubuntu® 24.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁴For detailed OS/hardware support information for Linux, see:

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors Overview^{1,2,3,4,5,6}

Intel® Core™ Ultra 9 Processor 285K with Intel® Graphics (3.2 GHz E-core base frequency, 3.7 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.5 GHz P-core Max Turbo frequency, 36 MB L3 cache, 8 P-cores and 16 E-cores, 24 threads) Intel® Core™ Ultra 9 Processor 285 with Intel® Graphics (1.9 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36 MB L3 cache, 8 P-cores and 16 E-cores, 24 threads) Intel® Core™ Ultra 7 Processor 265K with Intel® Graphics (3.3 GHz E-core base frequency, 3.9 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 30 MB L3 cache, 8 P-cores and 12 E-cores, 20 threads) Intel® Core™ Ultra 7 Processor 265 with Intel® Graphics (1.8 GHz E-core base frequency, 2.4 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 30 MB L3 cache, 8 P-cores and 12 E-cores, 20 threads) Intel® Core™ Ultra 5 Processor 245K with Intel® Graphics (3.6 GHz E-core base frequency, 4.2 GHz P-core base frequency, up to 4.6



Overview

GHz E-core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 14 threads) Intel® Core™ Ultra 5 Processor 245 with Intel® Graphics (3.0 GHz E-core base frequency, 3.5 GHz P-core base frequency, up to 4.5 GHz E-core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 14 threads) Intel® Core™ Ultra 5 Processor 235 with Intel® Graphics (2.9 GHz E-core base frequency, 3.4 GHz P-core base frequency, up to 4.4 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 14 threads) Intel® Core™ Ultra 5 Processor 225 with Intel® Graphics (2.7 GHz E-core base frequency, 3.3 GHz P-core base frequency, up to 4.4 GHz E-core Max Turbo frequency, up to 4.9 GHz P-core Max Turbo frequency, 20 MB L3 cache, 6 P-cores and 4 E-cores, 10 threads)

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode. ⁶Features and software that require a NPU may require software purchase, subscription or enablement by a software or platform provider, and third party software may have specific configuration or compatibility requirements. Performance varies by use, configuration, and other factors.

Expansion Slots (see Slot 1: system board section for PCIe Gen5 x16

more details) Slot 2:

PCIe Gen4 x1 - with x4 Connector

Slot 3:

PCIe Gen4 x4 - with x16 Connector

Slot 4: PCIe Gen4 x4

Expansion Bays (see 1 internal 3.5" bays (Include a carrier)

storage section for more 1 external 3.5" bays

details) 1 dedicated 9.5mm slim optical disk drive bay

Front I/O 4 SuperSpeed USB Std-A 10Gbps port:

2 SuperSpeed USB Type-C® 20Gbps port (charge supports up to 5V/3A)

Internal I/O [5] Serial port

Rear I/O 2 SuperSpeed USB Std-A 10Gbps port; 3 High-speed USB Std-A 480Mbps port



Overview

Optional I/O Flex IO, choice of:

> 1 Dual SuperSpeed USB Std-A 5Gbps port, 1 SuperSpeed USB Type-C® 10Gbps port (Alt Mode DisplayPort™1.4 with 15W Output) 1, 1 Dual SuperSpeed USB Type-C® 10Gbps port1, 1 Thunderbolt™ 4 port (40Gbps)1, 1 USBbased Serial port, 1 Displayport 2.1 port, 1 HDMI 2.1 port, 1 VGA port, (1) 1GbE NIC, (1) 1Gbps Fiber LC NIC*, (1) 2.5GbE NIC1, (1) 10GbE NIC*1, (1) Dual-port 10GbE NIC*, (1) Dual 1GbE NIC, (1) Dual Port 10/25GbE SFP28 * Flex IO2, choice of:

1 Dual SuperSpeed USB Std-A 5Gbps ports, 1 USB-based Serial port, (1) 1Gbps Fiber LC NIC (FLY USB Type)

Modern standby feature was not compatible risk (detail see NETWORKING / COMMUNICATION).

¹Component will be ready in 2025Q3

On-board RAID Support Factory integrated RAID 0, 1 for NVME drives (RAID 5, 10 Intel support)

Factory integrated RAID 0, 1 for SATA data drives

Chassis Dimensions (H x H: 15.2" [388mm] W: 6.9" [175mm] $W \times D$

D: 16.7" [426mm] (Standard desktop orientation)

Packaged Dimensions H:11.61" [295 mm]

W:23.23" [590 mm]

D:19.3" [490 mm] (Standard desktop orientation)

Rack Dimensions 4U, 1 units per slide rail kit(Standard EIA-310-D 19" Rack)

Weight Exact weights depend upon configuration (System weight only).

Starting at 8.6kg (19.02lbs.)s

Operating: 5° to 35° C (40° to 95° F) **Temperature**

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every

305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 8% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 8% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non- Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) pressurized)6

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Power Supply 1200W wide-ranging, active Power Factor Correction, 92% Efficiency. 700W wide-ranging, active Power Factor

Correction, 92% Efficiency. 500W wide-ranging, active Power Factor Correction, 92% Efficiency.

NOTE: The Power Supply Efficiency Report for the 1200W 92% Efficiency, 700W 92% Efficiency and 500W 92%

Efficiency Power Supply may be found at the following links:

https://www.pluqloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



Overview

Backup Devices

Chipset Intel® W880 Chipset

Memory 4 DIMM slots supporting up to 192GB nECC at launch (256 GB later) or up to 128 GB ECC, DDR5 unbuffered DIMM

memory.

Max memory speed will run at 5600 MT/s based on system configuration. See Supported Components /

Memory Section for details.



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Core™ Ultra Desktop Processors (series 2)				
	Intel® Core™ Ultra 9 285K Processor	Υ	N		
	Intel® Core™ Ultra 9 285 Processor	Υ	N		
	Intel® Core™ Ultra 7 265K Processor	Υ	N		
	Intel® Core™ Ultra 7 265 Processor	Υ	N		
	Intel® Core™ Ultra 5 245K Processor	Υ	N		
	Intel® Core™ Ultra 5 245 Processor	Υ	N		
	Intel® Core™ Ultra 5 235 Processor	Υ	N		
	Intel® Core™ Ultra 5 225 Processor	Υ	N		1

NOTE 1: support only non-ECC memory

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
:	8TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z273AA
	2TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z274AA
1	HP 1TB Enterprise SATA 7200 HDD	Υ	Υ	WOR10AA
	4TB 7200 RPM SATA 3.5in Enterprise HDD	Υ	Υ	K4T76AA
	12TB 7200 RPM SATA-6G 3.5in Enterprise HDD	Υ	Υ	5S461AA
9 1 9 1	HP Z Turbo Drive 1TB 2280 PCIe-4x4 SED OPAL2 TLC Z2 Kit SSD HP Z Turbo Drive 2TB 2280 PCIe-4x4 SED OPAL2 TLC Z2 Kit SSD HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Y Y Y Y Y	Y Y Y Y Y	223A3AA 223A4AA 201F5AA 201F8AA 201F9AA 201G0AA



Supported Components

Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA
Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA
256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Υ	Υ	4M9Z1AA
512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Υ	Υ	4M9Z2AA
1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Υ	Υ	4M9Z3AA
HP CRU Secure High Performance Storage M.2 2TB Storage Module	Υ	Υ	56Q87AA
HP CRU Secure High Performance Storage M.2 1TB Storage Module	Υ	Υ	56Q88AA
HP CRU Secure High Performance Storage M.2 512GB Storage Module	Υ	Υ	56Q89AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Υ	Υ	5S492AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Υ	Υ	5S496AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	5S497AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z2 Kit SSD	Υ	Υ	5S498AA
Z Turbo 512GB 2280 PCIe-4x4 TLC China SSD Module	Υ	Υ	906H1AA
Z Turbo 1TB PCIe-4x4 TLC China SSD Module	Υ	Υ	906H6AA
Z Turbo 2TB PCIe-4x4 TLC China SSD Module	Υ	Υ	906J0AA
HP Z Turbo 2TB PCIe-4x4 TLC China Z2 Kit SSD	Υ	Υ	906J1AA
256GB 2280 PCIe-4x4 NVMe Value M.2 China Z2 SSD Module	Υ	Υ	906J7AA
512GB 2280 PCIe-4x4 NVMe Value M.2 China Z2 SSD Module	Υ	Υ	906K1AA
1TB 2280 PCIe-4x4 NVMe Value M.2 China Z2 SSD Module	Υ	Υ	906K2AA
HP Z Turbo 1TB 2280 PCIe-5x4 TLC M.2 Z2 G12 TWR Kit SSD	Υ	Υ	B11F4AA
HP Z Turbo 1TB 2280 PCIe-5x4 SED OPAL2 TLC M.2 Z2 G12 TWR Kit SSD	Υ	Υ	B11F5AA
HP Z Turbo 2TB 2280 PCIe-5x4 TLC M.2 Z2 G12 TWR Kit SSD	Υ	Υ	B11F6AA
HP Z Turbo 2TB 2280 PCIe-5x4 SED OPAL2 TLC M.2 Z2 G12 TWR Kit SSD	Υ	Υ	B11F7AA



Supported Components

Graphics		Factory Configured	Option Kit	Option Kit Part Number		Support Notes
Graphics Cable	HP DisplayPort To VGA Adapter	N	Υ	AS615AA		
Adapters	HP USB-C to DisplayPort Adapter	N	Υ	4SH08AA		
	HP USB-C to HDMI Adapter	N	Υ	4SH07AA		
	HP USB-C to VGA Adapter	N	Υ	4SH06AA		
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA		
	HP DisplayPort to DVI-D Adapter	Υ	N			
	HP DP to HDMI 2.0	Υ	N			
Entry 3D	NVIDIA RTX A400 4 GB with Mini Bracket 4mDP Graphics	Υ	Υ	AV8J3AA	2	
Mid-range 3D	NVIDIA RTX A1000 8 GB with Mini Bracket 4mDP Graphics	Υ	Υ	AV8J4AA	2	
	NVIDIA RTX 2000 Ada 16 GB 4mDP Graphics	Υ	Υ	8D6B8AA	2	
High-End 3D	NVIDIA RTX 5880 Ada 48 GB 4DP Graphics	Υ	Υ	9Z7P5AA	1	
	NVIDIA RTX 6000 Ada 48 GB 4DP Graphics	Υ	Υ	79C23AA	1	
	NVIDIA RTX 4000 Ada 20 GB 4DP Graphics	Υ	Υ	8D6B7AA	2	
	NVIDIA RTX 4500 Ada 24 GB 4DP Graphics	Υ	Y	8D6C1AA	1	
	NVIDIA RTX 5000 Ada 32 GB 4DP Graphics	Υ	Υ	8D6B6AA	1	
	AMD Radeon Pro W7900 DS 48 GB 3DP+1mDP Graphics	Υ	Υ	В5СН6АА		

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 48GB DDR5 (1x48GB) 5600 UDIMM NECC Memory	Υ	Υ	8F070AA	



Supported Components

8GB DDR5 (1x8GB) 5600 UDIMM NECC Memory	Υ	Υ	A9TF0AA	
16GB DDR5 (1x16GB) 5600 UDIMM NECC Memory	Υ	Υ	A9TF1AA	
16GB DDR5 (1x16GB) 5600 UDIMM ECC Memory	Υ	Υ	A9TF2AA	1
32GB DDR5 (1x32GB) 5600 UDIMM NECC Memory	Υ	Υ	A9TF3AA	
32GB DDR5 (1x32GB) 5600 UDIMM ECC Memory	Υ	Υ	A9TF4AA	1

Note 1: ECC memory is supported

Optical and		Factory		
Removable Storage		Configured	Option Kit	Option Kit Part Number
	HP USB External DVDRW Drive	N	Υ	F2B56AA
	HP USB External DVDRW Drive	N	Υ	Y3T76AA
	HP CRU 0X328 3.5 in Front Removable Frame/Carrier	Υ	Υ	4N012AA

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Z2 G1i Single 1Gbps Fiber NIC USB FLY Adapter	Υ	Υ	W8X25AA
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Υ	436M8AA
	HP 10GBase-T Flex IO	Υ	Υ	56Q71AA
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA
	HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Υ	Υ	860T8AA
	HP Z2 2.5GbE LAN Flex Port1	Υ	Υ	B96W7AA
	Intel Ethernet I350-T4 4-Port 1Gb NIC	N	Υ	W8X25AA
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA
	Intel X550 10GBASE-T Dual Port NIC1	Υ	Υ	1QL46AA
	HP 25GbE SFP28 LC Fiber Optic Transceiver	Υ	Υ	860T9AA
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	1QL46AA
	Intel® Wi-Fi 6E AX211 BT 5.3 wireless card M.2 non-vPro	Υ	N	
	Intel® Wi-Fi 7 BE200 BT 5.4 wireless card M.2 non-vPro	Υ	N	

NOTE: Specific Network on Modern standby feature Support limitation Legacy Card AT-2911T2/901 and INTEL I350-T4 and INTEL X550-T2 and 10GBase-T FLEX IO and NVDIA CX-6 DX Dual 25GbE NIC do not support modern standby. And system equipped with those non modern standby network card, when monitor off and it is not really entered Modern standby state for wake-up function support, another path suggestion is Customer can use Onboard



Supported Components

HP 125 Wired Mouse

Lan for Wake event instead of legacy function WOL limitation because those commodities might not meet the required compliance standards in system modern standby configuration.

¹Component will be ready in June

Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP 685 Comfort Dual-Mode Keyboard	N	Υ	8T6L9UT
	HP 725 Multi-Device Rechargeable Wireless Keyboard	N	Υ	9T5B2AA
	HP Bus Slim v2 Smart Card USB Keyboard	Υ	Υ	A71J9AA
	HP 125 G2 USB Wired Keyboard	Υ	Υ	AY2Y7AA
	HP 320K G2 USB Wired Keyboard	Υ	Υ	9SR37UT
	HP 685 Comfort Dual-Mode Keyboard and Mouse Combo	N	Υ	8T6L7UT
	HP 725 Multi-Device Rechargeable Wireless Keyboard and Mouse Combo	Y	Y	9T5B0UT
	HP 655 Wireless Keyboard and Mouse Combo G2	N	Υ	4R009UT
	HP Wired Desktop 320MK Mouse and Keyboard G2	N	Υ	9SR36UT
	HP Wired 320M Mouse	Υ	Υ	9VA80AA
	HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA
	HP 128 LSR Wired Mouse	Υ	Υ	265D9AA

Flex Module (Rear IO)		Factory		
		Configured	Option Kit	Option Kit Part Number
HP 1GbE LAN Flex	x Port 2020	Υ	Υ	141J6AA
HP Flex 1GbE Fibe	er LC Single Port	Υ	Υ	20J15AA
HP Serial Port v3	Flex IO	Υ	Υ	5B895AA
HP 10GBase-T Flo	ex IO	Υ	Υ	
HP Z2 2.5GbE LAN	N Flex Port	Υ	Υ	
Serial Port FLY Flo	ex IO	Υ	N	
Dual Type-A 3.2 (Gen 1 FLY Flex IO	Υ	N	

Other Hardware Factory Option Kit Option Kit Part Number



265A9AA/AT/UT

Supported Components

	Configured		
HP Parallel PCIe x1 Card	Υ	Υ	N1M40AA
HP Remote System Controller	Υ	Υ	7K6D7AA
HP Remote System Controller Main Board Adapter	Υ	Υ	7K6D8AA
HP Integrated Remote System Controller	Υ	Υ	7K6D9AA
HP Z2 2nd serial port adapter	Υ	Υ	141K8AA
HP Z2 TWR G1i HDD Cable Kit	N	Υ	B5DU5AA
HP Rack Cable Management Arm	N	Υ	35Z34AA
HP Dual TBT5 PCIe x4 Low Profile Card	Υ	Υ	B15HRAA

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Z2 TWR Rail Rack Kit	N	Υ	B11FPAA
	HP Business PC Security Lock V3 Kit	N	Υ	3XJ17AA

Software	Factory Configured	Option Kit	Support Notes
	Υ	N	1
HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
HP PC Hardware Diagnostics Windows	Υ	N	
HP Wolf Security	Υ	N	3
HP Notifications	Υ	N	
HP Desktop Support Utility	Υ	N	
HP Documentation	Υ	N	
myHP	Υ	N	
Kingsoft WPS Office	Υ	N	4
Z by HP Data Science Stack Manager	Υ	N	5
HP Image Assistant	N	N	
HP Support Assistant	N	N	1

[1]Supported with Windows only. Also available as a free download from https://www.hp.com/us-en/workstations/performance-advisor.html

[2]Windows OS only

[3]Not available in Russia

[4]Only available in China



Supported Components

[5]Optional software

Operating Systems

Windows 11 Pro 641

Windows 11 Home 64 - HP recommends Windows 11 Pro1

Linux®-ready4

Ubuntu® 24.04 LTS^{2,3}

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 11 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

Not all features are available in all editions or versions of Ubuntu®. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requires may apply over time for updates.
 A certified preloaded version of Ubuntu® 24.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁴For detailed OS/hardware support information for Linux, see:

http://www.hp.com/support/linux_hardware_matrix

HP BIOS

Additional HP BIOS Features: • Power-On password – Helps prevent an unauthorized user from powering on the system.

- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - -Power to expansion connectors / slots
 - -Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - -USB charging ports

HP Performance Control Modes

HP Z Desktop Workstations offers Performance Control Modes in the F10 BIOS menu. Z2 G1i offers Quiet Mode,



Supported Components

Performance Mode, Rack Mode, and High-Performance Mode. HP recommends using High Performance Mode unless you have concerns about acoustics in an open office environment. Customers can achieve CPU performance gains in multithreaded workloads using High Performance Mode over Performance Mode*. High Performance Mode is configured as default from the factory.

How to Set HP Performance Control Modes in HP F10 BIOS Menu

In the F10 BIOS Menu, the setting titled "Performance Control" is adjustable to High Performance Mode, Performance Mode or Quiet Mode. These modes are choice points for performance and acoustic tradeoffs based on user needs or recommended balanced conditions in performance and noise optimization.

At startup, push the F10 key while system is booting to get to the BIOS Menu. Go to \rightarrow Advanced -> System Options ->scroll down and choose "Performance Control"

Set the Performance Mode you desire and then go back to Main->Save Changes and Exit -> Yes The machine will restart in the mode you've chosen.

How to change Performance Modes in HP Performance Advisor software?

Select BIOS Settings -> Advanced -> System Options -> Performance Controls

The machine will restart in the mode you've chosen.

For more information on performance control modes, please see the white paper called, HP Performance Control Modes for Z Desktop Workstations.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant 1

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

myHP

WSL/Ubuntu Data Science Stack

HP Privacy Settings

Manageability Features

HP Driver Packs²



Supported Components

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit 3

HP Client Catalog (download)

HP Image Assistant (download)

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere4

HP BIOS Configuration Utility (download)

Client Security Software

HP Client Security Suite⁵ including: (including Credential Manager, HP Password Manager⁶, HP Spare Key) HP Power On Authentication Microsoft Defender⁷

Security Management

HP Secure Erase⁸

HP Wolf Pro Security Edition (optional) 9

HP Wolf Security for Business¹⁰ Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run¹³

HP Sure Recover¹⁴

HP Sure Start¹⁵

HP Tamper Lock

HP Sure Admin 16

HP Client Security Manager¹⁷

Hood Sensor Optional Kit

²HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

³HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html ⁴ HP BIOSphere features may vary depending on the platform and configurations.

⁸ HP Secure Erase - -or the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "C" ear"



¹ HP Support Assistant requires Windows and Internet access.

⁵ HP Client Security Manager requires Windows and is available on the select HP PCs.

⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

⁷ Microsoft Defender Opt in and internet connection required for updates.

Supported Components

"anitation method. HP Secure Erase does not support platforms with Intel® Optane.

⁹HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

¹⁰ HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features

11 HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

¹³ HP Sure Run is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors ¹⁴ HP Sure Recover is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module

¹⁵ HP Sure Start is available on select HP PCs and workstations. See product specifications for availability.

¹⁶ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁷ HP Client Security Manager requires Windows and is available on the select HP PCs.



System Technical Specifications

System Board

System Board Form

421.08mm X 273.80mm X 1.55mm **Factor**

Processor Socket Single LGA-1851

CPU Bus Speed DMI GEN4

Chipset Intel® W880 Chipset

Super I/O Controller Nuvoton SIO24

Memory Expansion Slots 4 DDR5 memory slots

Memory Type Supported DDR5, UDIMM (Unbuffered), ECC& non-ECC

Memory Modes Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported $_{5600MT/s\ DDR5}$

Memory Protection ECC available on data

Maximum Memory 256GB

Memory Configuration

(Supported)

8GB, 16GB, 32GB, 48G and 64GB non-ECC/16GB, 32GB ECC unbuffered DIMMs are supported.

ECC and non-ECC memory DIMMs cannot be mixed on the same system.

Two channels of DDR5 memory are supported. To realize full performance at least one DIMM must be inserted into each channel. Single DIMM per channel must be installed into furthest slot from CPU(DIMM 1 or 3).

The system speed will be determined by a number of key factors:

Module Configuration	Description of configuration	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	5600MHz
Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system. Memory speed may also vary depending on vendor module mix.	4800MHz
Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB, 48GB and 64GB) installed in a system	4400MHz

When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

PCI Express Connectors

- (1) PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length)
- (1) PCI Express Gen4 slot x4 mechanical/x1 electrical (full height, full length, open-ended)
- (1) PCI Express Gen4 slot x16 mechanical/x4 electrical (full height, full length)



System Technical Specifications

(1) PCI Express Gen4 slot x4 mechanical/ x4 electrical (full height, full length, open-ended)

(1) M.2 2280 Storage (PCIe Gen5 x4)

(1) M.2 2280 Storage (PCIe Gen4 x4)

(1) M.2 2280 Storage (PCIe Gen4 x4)

(1) M.2 2230 WLAN (PCIe Gen4 x1+ Intel CNVi)

Supported Interfaces

Integrated RAID RAID 0, 1 (RAID 5, 10 Intel support)

Integrated Graphics Intel® Graphics- (on Core™ Ultra 9 /Core™ Ultra 7/Core™ Ultra

5 processors)

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics

display.

Support for Microsoft DirectX 12, OpenGL 4.6, OpenCL 3.0

and Vulkan on Intel® Graphics;

2x DP 1.4 graphics ports integrated in motherboard; Supports up to four simultaneous displays with Multiple Stream Transport (MST) across VGA*/DVI*/HDMI* outputs. Max resolution supported on onboard DP 1.4/HBR3 ports:

3840 x2160 (4K) @ 60Hz.

Max resolution supported on flexIO DP 2.1/UHBR20 ports: 7680*4320 (8K) @60Hz compressed, 5K120Hz compressed.

Network Controller Integrated Ethernet PHY Connection I219LM. Management

capabilities: WOL, PXE 2.1 and AMT 19

Serial 1 internal header (requires optional Serial Port Adapter Kit)

2^{nd S}erial USB-based Serial port option through Flex IO

USB-based Serial port option through Flex IO2

HD Integrated Audio Integrated Ethernet PHY Connection I219LM. Management

capabilities: WOL, PXE 2.1 and AMT 16

USB Connector(s) Front 4 SuperSpeed USB Std-A 10Gbps port; 2 SuperSpeed USB

Type-C[®] 20Gbps port (charge supports up to

5V/3A)

Rear 2 SuperSpeed USB Std-A 10Gbps port; 3 High-speed USB

Std-A 480Mbps port

Flex IO, choice of:

1 Dual SuperSpeed USB Std-A 5Gbps port, 1 SuperSpeed USB Type-C® 10Gbps port (Alt Mode DisplayPort™1.4 with 15W Output) 1, 1 Dual SuperSpeed USB Type-C® 10Gbps port 1, 1

Thunderbolt™ 4 port (40Gbps)¹



System Technical Specifications

Flex IO2, choice of:

1 Dual SuperSpeed USB Std-A 5Gbps ports

¹Component will be ready in 2025Q3

HD Integrated Audio Realtek ALC3205, 2.0W internal mono speaker

Flash ROM Yes **CPU Fan Header** Yes **Memory Fan Header** None

Chassis Fan Header 1 Rear System Chassis Fan Header, 1 Side chassis Fan Header, 1 Front chassis Fan Header, 2 Bottom

chassis Fan Header

Front PCI Fan Header None

Front Control

Panel/Speaker Header Yes

CMOS Battery Holder - -

ithium

Integrated Trusted

Platform Module

Integrated TPM 2.0 Convertible to FIPS 140-2 Certified modeThe TPM module disabled where

restricted by law

Yes

Power Supply Headers Yes

Power Switch, Power LED & Hard Drive LED Header Yes **Clear Password Jumper** None

Keyboard/Mouse USB or PS/2 (option)

Power Supply 1200W wide-ranging, active Power Factor Correction, 92% Efficiency. 700W wide-ranging, active

Power Factor Correction, 92% Efficiency. 500W wide-ranging, active Power Factor Correction, 92%

Efficiency.

NOTE: The Power Supply Efficiency Report for the 1200W 92% Efficiency, 700W 92% Efficiency and

500W 92% Efficiency Power Supply may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

System Configurations

Intel Core Ultra 5 10C 3.3GHz LGA 65 W **Processor Info**



System Technical Specifications

HP Z2 TWR G1i	Memory Info	1x 16GB DDR5 ECC
Configuration #1	Graphics Info	1x NVIDIA RTX A400
	Disks/Optical/Floppy	1x 256GB PCIe-4x4 2280 Value M.2 SSD
	PSU	500W
	Other	NA

Energy Consumption	115 VAC		230 VAC		100 VAC		
(Watts)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows long Idle (S0)	2.3		2.5		2.23	
	Windows short Idle (S0)	13.8		13.91		13.18	
	Windows Busy Typ (S0)	139.2		140.9		138.9	
	Windows Busy Max (S0)	145.5		146.8		144.2	
	Sleep (S3)	2.3	2.3	2.4	2.4	2.3	2.3
	Off (S5)	0.69	0.67	0.69	0.68	0.67	0.67
	Zero Power Mode (EuP)	0.7	25	0.24		0.25	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	7.8476		8.53		7.609	
	Windows short Idle (S0)	47.0856		47.4609		44.9702	
	Windows Busy Typ (S0)	474.9504		480.7508		473.9268	
	Windows Busy Max (S0)	496.446		500.8816		492.0104	
	Sleep (S3)	7.8476	7.8476	8.1888	8.189	7.8476	7.8476
	Off (S5)	2.3202	2.286	2.3543	2.3202	2.286	2.3543
	Zero Power Mode (EuP)	0.8	353	0.8189		0.853	

HP Z2 TWR G1i	Processor Info	Intel Core Ultra 7 20C 2.4GHz LGA 65W
	Memory Info	1x 32GB DDR5 NECC
Configuration #2	Graphics Info	1x NVIDIA RTX A2000
	Disks/Optical/Floppy	1x 1TB 2280 PCIe-4x4 Val M.2 SSD
	PSU	700W
	Other	NA

Energy Consumption	115 VAC	230 VAC	100 VAC



System Technical Specifications

(Watts)	LAN	LAN	LAN	LAN	LAN	LAN	
	Enabled	Disabled	Enabled	Disabled	Enabled	Disabled	
Windows long Idle	e (SO) 2.	2.76		59	2.0	53	
Windows short Idl	e (S0) 13	.96	14.	25	12.	85	
Windows Busy Typ	p (S0) 196	196.500		198.600		900	
Windows Busy Ma	x (S0) 208	3.300	210.	600	206.	950	
Sleep (S3)	2.76	2.76	2.69	2.69	2.61	2.61	
Off (S5)	0.68	0.63	0.69	0.62	0.68	0.61	
Zero Power Mode	(EuP) 0.	0.26		0.27		0.25	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN	LAN LAN		LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	9.4171		9.1783		8.9736	
	Windows short Idle (S0)	47.6315		48.621		43.8442	
	Windows Busy Typ (S0)	670.458		677.6232		664.9988	
	Windows Busy Max (S0)	710.7196		718.5672		706.1134	
	Sleep (S3)	9.4171	9.4171	9.1783	9.1783	8.9053	8.9053
	Off (S5)	2.3202	2.1496	2.3543	2.1154	2.3202	2.0813
	Zero Power Mode (EuP)	0.8	871	0.9212		0.853	

	Processor Info	Intel Core Ultra 9K 24C 3.7GHz LGA 125W							
HP Z2 TWR G1i	Memory Info	4x 48GB DDR5 NECC							
Configuration #3	Graphics Info	1x NVIDIA RT	X A6000						
	Disks/Optical/Floppy	1x 4TB 2280 PCIe-4x4 OPAL2 M.2 SSD 2x HDD 12TB 7200RPM SATA-6G Ent 3.5in							
	PSU	1200W							
	Other	NA							
Energy Consumption		115 VAC		230 VAC		100 VAC			
(Watts)		LAN	LAN	LAN	LAN	LAN	LAN		
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled		
	Windows long Idle (S0)	6.	57	6.69		6.35			
	Windows short Idle (S0)	44	.53	45.96		42.81			
	Windows Busy Typ (S0)	510.600		517.400		502.980			
	Windows Busy Max (S0)	530.800		538	.100	521.300			
	Sleep (S3)	6.57	6.57	6.69	6.69	6.35	6.35		



System Technical Specifications

Off (S5)	0.67	0.63	0.68	0.62	0.65	0.6
Zero Power Mode (EuP)		25	0.	25	0.7	24

Heat Dissipation	ion 115 VAC		230 VAC		100 VAC		
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	22.4168 151.9364		22.8263		21.6662	
	Windows short Idle (S0)			156.8155		146.0677	
	Windows Busy Typ (S0)	1742.1672		1765.3688		1716.1678	
	Windows Busy Max (S0)	1811.	0896	1835.9972		1778.6756	
	Sleep (S3)	22.4168	22.4168	22.8263	22.8263	21.6662	21.6662
	Off (S5)	2.286	2.1496	2.3202	2.1154	2.2178	2.0472
	Zero Power Mode (EuP) 0.853		53	0.853		0.8189	

NOTE: The Power Supply Efficiency report may be found at the following links:v

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

Operating Voltage Range 90-269VAC

Rated Voltage Range 100-240VAC

Rated Line Frequency 50-60 Hz

Frequency Range

47-63Hz

Rated Input Current 14-8A @100-240VAC

Heat Dissipation Typical: 1765.3688 btu/hr (445.226 kcal/hr)

Maximum: 1835.9972 btu/hr (463.0385 kcal/hr)

ENERGY STAR® certified

(Config Dependent)

CECP Compliant @ 220V YES

FEMP Standby Power

Compliant

Yes, with Wake-on-LAN disabled: <1W in S4/S5 - Power Off

Built-in Self Test (BIST)

LED

Yes

Yes

Surge Tolerant Full Yes

Ranging Power Supply

(withstands power surges

up to 2000V)



System Technical Specifications

Hood Lock Header

Yes

ErP Lot 6- Tier 1

Yes

Compliance @ 230V (<1W

in S5 - -Power Off)

Yes

ErP Lot 6- Tier 2

Compliance @ 230V (<0.5W in S5 - Power Off)

Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)

System Configuration
(Entry-level)

Processor Info	Intel CPU Core U5-225/65W
Memory Info	Micron 5600 32GB x1
Graphics Info	NA
Disks/Optical	PHISON GEN4 M.2 SSD 4TB x1
Power Supply	700W

n	erl	ared	l Noise	Emissions
v	CLI	areu	i ianize	EIIIISSIUIIS

IS		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.47	15.8
	Hard drive Operating (Drive Random Seek)	NA	NA
	Hard drive Operating (Active mode)	3.6	15.76

System Configuration (Mid-end)

Processor Info	Intel Core Ultra 9 285 /65W
Memory Info	Micron 5600 32GB x4
Graphics Info	NVIDIA RTX 5000ada
	PHISON GEN4 M.2 SSD 4TB x2
Disks/Optical	PHISON GEN5 M.2 SSD 2TB x1
Power Supply	700W

Declared Noise Emissions

IS		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	3.91	22.42	
	Hard drive Operating (Drive Random Seek)	NA	NA	
	Hard drive Operating	4.07	23.46	



System Technical Specifications

(Active mode)	

System Configuration (High-end)	Processor Info	Intel Core Ultra 9 285 /125W
	Memory Info	Micron 5600 32GB x4
	Graphics Info	NVIDIA RTX 5000ada
		PHISON GEN4 M.2 SSD 4TB x2
	Disks/Optical	PHISON GEN5 M.2 SSD 2TB x1
	Power Supply	700W

Declared Noise		Sound Power (LWAd, bels)	Deskside Sound Pressure
Emissions			(LpAm, decibels)
	Idle	3.9	22.02
	Hard drive Operating	NA	NA
	(Drive Random Seek)		
	Hard drive Operating	4.0	22.66
	(Active mode)		

Environmental
Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 8% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 8% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Cooling for details.

Dynamic Shock

Operating: 1/2-sine: 40g, 2ms

Non-operating: 1/2-sine: 165 cm/s, 2-3ms

square: 422 cm/s, 30g

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to $0.00025g^2/Hz$ Non-operating random: 2.0g (rms), 5-500 Hz, up to $0.0150 g^2/Hz$

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1°C (1.8°F) for every 305 m (1,000 feet) increase in elevation,



System Technical Specifications

up to 3048 m (10,000 feet)

Physical Security and Serviceability

Access Panel Tool-less **Optical Drive** Tool-less

Hard Drives Internal bay:Tool-less

External bay: Acoustic damping screws

Expansion Cards Tool-less

Processor Socket Tool-less, except for the processor heatsink **Blue User Touch Points** Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes, PSU connectors are printed with sequence numbers to corresponding board connectors.

and Connectors

Memory Tool-less **System Board** Screw-In

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

0.22-in diameter padlock loop at rear of system

Cable Lock Support Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Sensor

No

Solenoid Lock and Hood Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through

software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed.

CPUs and Heatsinks A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Internal Speaker

Power Supply Fans 70mm x 70mm x 25mm 4-wire PWM (non-serviceable)

Access Panel Key Lock Nο

Integrated Chassis

Rear Recessed Handle

Handles **Power Supply**

Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (optional), front (full-length cards with extender) Power-On Password Yes, prevents an unauthorized person from booting up the workstation



System Technical Specifications

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

Service, Support, and Warranty

On-site Warranty and Service¹: One-year (1-1-1), limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - -5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries. HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

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Please contact techregshelp@hp.com



System Technical Specifications

BIOS

BIOS 64-bit Services BIOS supports 64-bit Operating systems.

PCI 3.0 Support Full BIOS support for PCI Express through industry standard interfaces

ATAPI ATAPI Removable Media Device BIOS Specification Version 1.0.

WMI Support WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

Users can define a specific date and time for the system to power on. **BIOS Power On**

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with

Recovers system BIOS in corrupted Flash ROM.

Video **Replicated Setup**

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

Boot Control Disables the ability to boot from removable media on supported devices.

Memory Change Alert

Alerts management console if memory is removed or changed.

Thermal Alert Monitors the temperature state within the chassis. Three modes:

NORMAL – normal temperature ranges.

ALERTED – excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

SHUTDOWN – excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

Management Interface)

ACPI (Advanced Allows the system to enter and resume from low power modes (sleep states). Enables an operating

Configuration and Power system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Ownership Tag

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - -CPI

sleep state Modern standby)

Allows for very low power consumption with guick resume time.



System Technical Specifications

Remote System

Installation via F12 (PXE operating system.

2.1) (Remote Boot from

Server)

ROM revision levels

System board revision

level Start-up Diagnostics

(Power-on Self-Test)

Auto Setup when new

hardware installed

Localized ROM Setup

Asset Tag

Per-slot Control Adaptive Cooling

Pre-boot Diagnostics UEFI Specification

Revision

ACPI

ATA (IDE) **CD Boot**

EHCI PCI

PCI Express

SATA

SPD

Allows a new or existing system to boot over the network and download software, including the

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

Allows management SW to read revision level of the system board. Revision level is digitally encoded

into the HW and cannot be modified.

Assesses system health at boot time with selectable levels of testing.

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory.

Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "El Torito" Bootable CD-ROM Format Specification Version 1.0

Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI Local Bus Specification, Revision 2.3

2.9

PCI Power Management Specification, Revision 1.1

PCI Firmware Specification, Revision 3.0

PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0

Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s:

Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s:

Serial ATA Specification, Revision 3.0

JEDEC JESD300-5



System Technical Specifications

TPM Trusted Computing Group TPM Specification Version 2.0 (Nuvoton NPCT760HACYX or Infineon

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

> Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification

System Management BIOS Reference Specification, Version 3.8 **SMBIOS**

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

Eco-Label Certifications & Declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- **Product Carbon Footprint**
- At least 25% ocean bound plastic in the System Fan and 5% ocean bound plastic in the speaker1
- At least 90% ITE-Derived closed loop plastic²
- At least 60% post-consumer recycled plastic²
- At least 20% recycled metal3
- Low Halogen4
- 100% of HP paper-based packaging is from recycled or certified sustainable sources⁵
- Bulk packaging available

System Configuration The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".



System Technical Specifications

Energy Consumption
(in accordance with
US ENERGY STAR® tes

method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Sort idle)	44.5 W	45.2 W	43.7 W
Normal Operation (Long idle)	6.6W	6.6 W	6.6 W
Sleep	6.6 W	6.6 W	6.6 W
Off	0.7 W	0.7 W	0.7 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	152 BTU/hr	155 BTU/hr	149 BTU/hr
Normal Operation (Long idle)	23 BTU/hr	23 BTU/hr	23 BTU/hr
Sleep	22.6 BTU/hr	23 BTU/hr	22.6 BTU/hr
Off	2.4 BTU/hr	2 BTU/hr	2.4 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise	Sound Power	Sound Pressure
Emissions	(L _{WAd} , bels)	(L _{pAm} , decibels)
(in accordance with		
ISO 7779 and ISO		
9296)		
Typically Configured –	3.9	22.02



System Technical Specifications

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Fixed Disk – Random writes	4.2	25.46
Optical Drive –	4.0	22.66
Sequential reads		

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 95.8% recycle-able when properly disposed of at end of life.

Packaging Materials External:

PAPER/Corrugated 1316 gram
PAPER/Molded Pulp 1114 gram
PLASTIC/Polyethylene low density - 58 gram
-LDPE

The plastic packaging material contains at least 30% recycled content.

The corrugated paper packaging materials contains at least 64.8% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.



System Technical Specifications

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c05998906):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.



System Technical Specifications

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:

https://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c05403198

or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: HP Product Disassembly Instruction Website. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate **Environmental** Information

For more information about HP's commitment to the environment:

- Sustainable Impact Report
 - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843
- **Eco-label** certifications
 - https://www.hp.com/us-en/sustainable-impact/documentreports.html#filters_documents_reports-=document_typetype_energy_star,type_epeat,type_tcolSO
- ISO 14001 certificates
 - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932

footnotes

- 1. Percentage of ocean-bound plastic contained in each component varies by product. Ocean Bound plastic is expressed as a percentage of the total weight plastic. Ocean Bound plastic is based on the definition set by the UL2809 standard.
- 2. Recycled plastic is expressed as a percentage of the total weight plastic. Post-consumer recycled is based on the definition set in the EPEAT standard for computers, IEEE 1680.1-2018 standard.
- Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.
- 4. External power supplies, WWAN modules, power cords, cables and peripherals excluded. Service parts obtained after purchase may not be Low Halogen.
- 5. HP paper and fiber-based packaging for PCs, displays, home and office print, and supplies is reported by suppliers as recycled or certified, with a minimum of 97% by volume verified by HP. Packaging is the box that comes with the product and all paper-based materials inside the box. Packaging for personal systems accessories and spare parts is not included. Plastic cushions are made from >90% recycled plastic.

Manageability

Intel® Active

Intel® Active Management Technology (AMT) 1

(AMT)

Management Technology An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. Intel® AMT includes the following advanced management functions:



System Technical Specifications

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
- Hardware Inventory (includes BIOS and firmware revisions)
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL)
- Ipv6 Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back

Intel® vPro® Technology

The HP Z2 G1i Tower Workstation supports Intel® vPro® technology when configured as outlined below:

- Intel® Core™ Ultra 200S Series Processors product family featuring Intel® vPro® Technology
- Intel® W880 chipset
- Intel® I219LM GbE LAN

HP Image Assistant

Visit: http://ftp.hp.com/pub/caps-softpaq/cmit/HPIA.html

System Software

Manager

For questions or support for SSM, please visit: http://www.hp.com/go/ssm

¹Requires activation and a system with a corporate network connection, an Intel® AMT enabled chipset, and network hardware and software. For notebooks, Intel AMT may be unavailable or limited over a host OS-based VPN, when connecting wirelessly, on battery power, sleeping, hibernating, or powered off. Results dependent upon hardware, setup, and configuration. For more information, visit: https://www.intel.com/content/www/us/en/architecture-and-technology/intel-active-managementtechnology.html



Technical Specifications - Storage Drives

STORAGE

HP Z Turbo Drv PCIE-4X4 512GB TLC PCIe SSD

(Z2G1i)

Capacity 512GB **Protocol** PCle

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance150 TBWReliability1.5M Hours

Interface PCI Express 4.0 x4 electrica
Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 6400MB/s [1]

 Sequential Write
 3400MB/s [1]

 Random Read
 600K IOPS [1]

 Random Write
 600K IOPS [1]

HP Z Turbo Drv PCIE-4X4 1TB TLC PCIe SSD

(Z2G1i)

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance300 TBWReliability1.5M hours

Interface PCI Express 4.0 x4 electrica
Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 6500MB/s [1]

 Sequential Write
 5000MB/s [1]

 Random Read
 800K IOPS [1]

 Random Write
 800K IOPS [1]

*Actual performance may vary.

HP Z Turbo Drv PCIE-4X4 2TB TLC PCIe SSD (Z2G1i) Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance500 TBWReliability1.5M hours

InterfacePCI Express 4.0 x4 electricaOperating Temperature32° to 158° F (0° to 70° C)

Performance



^{*}Actual performance may vary.

Technical Specifications - Storage Drives

 Sequential Read
 6500MB/s [1]

 Sequential Write
 5000MB/s [1]

 Random Read
 800K IOPS [1]

 Random Write
 800K IOPS [1]

*Actual performance may vary.

HP Z Turbo Drv PCIE-4X4 4TB TLC PCIe SSD (Z2G1i) Capacity 1TB Protocol PCle

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance600 TBWReliability1.5M hours

Interface PCI Express 4.0 x4 electrica
Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 6500MB/s [1]

 Sequential Write
 5000MB/s [1]

 Random Read
 800K IOPS [1]

 Random Write
 800K IOPS [1]

*Actual performance may vary.

HP Z Turbo Drv PCIE-4X4 512GB TLC PCIe SED OPAL2 (Z2G1i) Capacity512GBProtocolPCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance150 TBWReliability1.5M hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 158° F (0° to 70° C)

Performance

Sequential Read6400MB/s [1]Sequential Write3400MB/s [1]Random Read600K IOPS [1]Random Write600K IOPS [1]Self-Encrypting Drive Support0PAL2

HP Z Turbo Drv PCIE-4X4 1TB TLC PCIe SED OPAL2

TTB TLC PCIe SED OPALZ
(Z2G1i)

Capacity 1TB
Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe



Technical Specifications - Storage Drives

NAND Type 3D TLC Endurance 300 TBW Reliability 1.5M hours

Interface PCI Express 4.0 x4 electrica **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance

Sequential Read6500MB/s [1]Sequential Write5000MB/s [1]Random Read800K IOPS [1]Random Write800K IOPS [1]Self-Encrypting Drive Support0PAL2

HP Z Turbo Drv PCIE-4X4 2TB TLC PCIe SED OPAL2 (Z2G1i) Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance500 TBWReliability1.5M hours

Interface PCI Express 4.0 x4 electrica
Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read6500MB/s [1]Sequential Write5000MB/s [1]Random Read800K IOPS [1]Random Write800K IOPS [1]Self-Encrypting Drive Support0PAL2

Actual performance may vary.

HP Z Turbo Drv PCIE-4X4 4TB TLC PCIe SED OPAL2 (Z2G1i) Capacity 4TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLCEndurance600 TBWReliability1.5M hours

InterfacePCI Express 4.0 x4 electricaOperating Temperature32° to 158° F (0° to 70° C)

Performance

Sequential Read 6500MB/s [1]
Sequential Write 5000MB/s [1]



^{*}Actual performance may vary.

Technical Specifications - Storage Drives

Random Read800K IOPS [1]Random Write800K IOPS [1]Self-Encrypting Drive Support0PAL2

Actual performance may vary.

256GB 2280 PCIe-4x4 Value M.2 SSD (Z2G1i)

Capacity 256GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 200TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 4.0 x4 electricaOperating Temperature32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 3100MB/s [1]

 Sequential Write
 1400MB/s [1]

 Random Read
 200K IOPS [1]

 Random Write
 400K IOPS [1]

Actual performance may vary.

512GB 2280 PCIe-4x4 Value M.2 SSD (Z2G1i)

Capacity 512GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrica
Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 3400MB/s [1]

 Sequential Write
 2500MB/s [1]

 Random Read
 380K IOPS [1]

 Random Write
 430K IOPS [1]

Actual performance may vary.

1TB 2280 PCIe-4x4 Value M.2 SSD (Z2G1i) Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)



Technical Specifications - Storage Drives

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 3400MB/s [1]

 Sequential Write
 2500MB/s [1]

 Random Read
 500K IOPS [1]

 Random Write
 440K IOPS [1]

Actual performance may vary.

HP Z Turbo Drv PCIE-5X4 1TB TLC PCIe SSD

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 5.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read 12000 MB/s*
Sequential Write 10000 MB/s*
Random Read 1500K IOPS*
Random Write 1300K IOPS*

Actual performance may vary.

HP Z Turbo Drv PCIE-5X4 2TB TLC PCIe SSD

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 5.0 x4 electricalOperating Temperature32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 12000 MB/s [1]

 Sequential Write
 11000 MB/s [1]

 Random Read
 1500K IOPS [1]

 Random Write
 1300K IOPS [1]

Actual performance may vary.

HP Z Turbo Drv PCIE-5X4 1TB Capacity 1TB



Technical Specifications - Storage Drives

TLC PCIe SED OPAL2 Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 5.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 12000 MB/s [1]

 Sequential Write
 10000 MB/s [1]

 Random Read
 1500K IOPS [1]

 Random Write
 1300K IOPS [1]

Self-Encrypting Drive Support OPAL2

Actual performance may vary.

HP Z Turbo Drv PCIE-5X4 2TB TLC PCIe SED OPAL2

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 5.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

 Sequential Read
 12000 MB/s [1]

 Sequential Write
 11000 MB/s [1]

 Random Read
 1500K IOPS [1]

 Random Write
 1300K IOPS [1]

Actual performance may vary.

512GB TLC PCIE Gen3x4 SED FIPS 140-2

Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 320 TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read up to 3400MB/s [1]



Technical Specifications - Storage Drives

Sequential Writeup to 2500MB/s [1]Random Read420K IOPS [1]Random Write635K IOPS[1]Self-Encrypting Drive SupportOPAL2/FIPS 140-2

Actual performance may vary.

1TB TLC PCIE Gen3x4 SED FIPS 140-2

Capacity 1TB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 1620 TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read 3400MB/s* [1]
Sequential Write 3000MB/s* [1]
Random Read 720K IOPS* [1]
Random Write 690K IOPS* [1]
Self-Encrypting Drive Support 0PAL2/FIPS 140-2

Actual performance may vary.

2TB TLC PCIE Gen3x4 SED FIPS 140-2

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 3140 TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read3400MB/s [1]Sequential Write3000MB/s [1]Random Read720K IOPS [1]Random Write690K IOPS [1]Self-Encrypting Drive Support0PAL2/FIPS 140-2

Actual performance may vary.

Citadel 512GB TLC PCIE Gen3x4 SED FIPS 140-2 Capacity 512GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard



Technical Specifications - Storage Drives

Controller NVMe NAND Type 3D TLC

Endurance 320 TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 3.0 x4 electricalOperating Temperature32° to 158° F (0° to 70° C)

Performance

Sequential Readup to 3400MB/s [1]Sequential Writeup to 2500MB/s [1]Random Read420K IOPS [1]Random Write635K IOPS[1]Self-Encrypting Drive SupportOPAL2/FIPS 140-2

Actual performance may vary.

Citadel 1TB TLC PCIE Gen3x4 SED FIPS 140-2

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 1620 TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read 3400MB/s* [1]
Sequential Write 3000MB/s* [1]
Random Read 720K IOPS* [1]
Random Write 690K IOPS* [1]
Self-Encrypting Drive Support 0PAL2/FIPS 140-2

Actual performance may vary.

Citadel 2TB TLC PCIE Gen3x4 SED FIPS 140-2

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 3140 TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 3.0 x4 electricalOperating Temperature32° to 158° F (0° to 70° C)

Performance

Sequential Read3400MB/s [1]Sequential Write3000MB/s [1]



Technical Specifications - Storage Drives

Random Read720K IOPS [1]Random Write690K IOPS [1]Self-Encrypting Drive Support0PAL2/FIPS 140-2

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity1TBProtocolSATAForm Factor3.5"ControllerAHCIReliability2.0M HoursRated Power On Hours8760/yrAnnualized Failure Rate (based<0.62%</th>

on Rated POH)

Width

Media Diameter3.5in; 8.9 cmPhysical Size4 in; 10.17cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Up to 600MB/s [1]

Synchronous Transfer Rate

(Maximum)

Buffer 128MB

Seek Time (typical reads, includes controller overhead,

including settling)

Single Track0.32ms [1]Average7.45ms [1]Full Stroke14.2ms [1]Rotational Speed7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance

Sequential Read up to 226MB/s[1]
Sequential Write up to 226MB/s[1]
Enterprise Class Features High Reliability

[1]Actual performance may vary.

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 2TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M Hours
Rated Power On Hours 8760/yr

Rated Power On Hours 8760/yr Annualized Failure Rate (based <0.62%



Technical Specifications - Storage Drives

on Rated POH)

Width

Media Diameter3.5in; 8.9 cmPhysical Size4 in; 10.17cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate Up to 600MB/s [1]

(Maximum)

Buffer 128MB

Seek Time (typical reads, includes controller overhead,

including settling)

 Single Track
 0.7ms [1]

 Average
 8.5ms [1]

 Full Stroke
 15.7ms [1]

 Rotational Speed
 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance

Sequential Readup to 226MB/s[1]Sequential Writeup to 226MB/s[1]Enterprise Class FeaturesHigh Reliability

[1]Actual performance may vary.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity4TBProtocolSATAForm Factor3.5"ControllerAHCIReliability2.0M HoursRated Power On Hours8760/yrAnnualized Failure Rate (based)<0.62%</th>

on Rated POH)

Width

Media Diameter3.5in; 8.9 cmPhysical Size4 in; 10.17cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate Up to 600MB/s [1]

(Maximum)

Buffer 128MB

Seek Time (typical reads, includes controller overhead,

including settling)

Single Track 0.7ms [1]



Technical Specifications - Storage Drives

 Average
 8.5ms [1]

 Full Stroke
 15.7ms [1]

 Rotational Speed
 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance

Sequential Readup to 226MB/s[1]Sequential Writeup to 226MB/s[1]Enterprise Class FeaturesHigh Reliability

[1]Actual performance may vary.

8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity8TBProtocolSATAForm Factor3.5"ControllerAHCIReliability2.0M HoursRated Power On Hours8760/yrAnnualized Failure Rate (based<0.62%</th>

on Rated POH)

Width

Media Diameter3.5in; 8.9 cmPhysical Size4 in; 10.17cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate Up to 600MB/s [1]

(Maximum)

Buffer 128MB

Seek Time (typical reads, includes controller overhead,

including settling)

 Single Track
 0.7ms [1]

 Average
 8.5ms [1]

 Full Stroke
 15.7ms [1]

 Rotational Speed
 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance

Sequential Readup to 226MB/s[1]Sequential Writeup to 226MB/s[1]Enterprise Class FeaturesHigh Reliability

[1]Actual performance may vary.



Technical Specifications - Storage Drives

12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity12TBProtocolSATAForm Factor3.5"ControllerAHCI

Reliability 2.0M Hours Rated Power On Hours 8760/yr Annualized Failure Rate (based <0.62%

on Rated POH)

Width

Media Diameter3.5in; 8.9 cmPhysical Size4 in; 10.17cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate Up to 600MB/s [1]

(Maximum)

Buffer 128MB

Seek Time (typical reads, includes controller overhead,

including settling)

 Single Track
 0.7ms [1]

 Average
 8.5ms [1]

 Full Stroke
 15.7ms [1]

 Rotational Speed
 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance

Sequential Read up to 226MB/s[1]
Sequential Write up to 226MB/s[1]
Enterprise Class Features High Reliability

[1]Actual performance may vary.



Technical Specifications - Graphics

AMD Radeon™ Pro W7900 48GB **Form Factor** Double slot, full-height, 11" length

Graphics Controller Power: 295 Watts

Cooling Solution: Active Fan Heatsink

Bus Type PCI Express 4.0 x 16 **Memory** 48GB GDDR6 Memory

Memory Bandwidth: 864 GB/s

Memory Width: 384 bit

Connectors 3x DisplayPort 2.1

1x Enhanced Mini DisplayPort 2.1

Requires 2x 8-pin auxiliary power connectors

Max simultaneous

displays

12288x6912 @ 120Hz

Available Graphics

Drivers

Windows 11
Windows 10
Linux® 64-bit

NVIDIA® RTX™ A400 4GB Form Factor

Graphics Controller

Half Height Single Slot (2.7" Height x 6.4" Length)

Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 8

Memory 4GB GDDR6

Memory Bandwidth: 96 GB/s

Memory Width: 64-bit

Connectors 4x Mini DisplayPort 1

Max simultaneous

displays

4x Mini DisplayPort 1.4a 4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz

2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A1000 8GB Form Factor
Graphics Controller

Half Height Single Slot (2.7" Height x 6.4" Length)



Technical Specifications - Graphics

Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 8

8GB GDDR6 Memory

Memory Bandwidth: 96 GB/s

Memory Width: 128-bit

Connectors 4x Mini DisplayPort 1.4a

Max simultaneous 4x 4096 x 2160 @ 120 Hz

displays 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Available Graphics Windows 10 64-bit

Drivers Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ 2000 Ada Form Factor

16GB

Half Height Dual Slot (2.7" Height x

6.7" Length)

Graphics Controller

Max Power: 70 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 8

Memory 16GB GDDR6

Memory Bandwidth: 224 GB/s

Memory Width: 128-bit

Connectors 4x Mini DisplayPort 1.4a

Max simultaneous 4x 4096 x 2160 @ 120 Hz

4x 5120 x 2880 @ 60 Hz

Windows 10 64-bit

2x 7680 x 4320 @ 60 Hz

Available Graphics

displays

Drivers Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

NVIDIA® RTX™ 4000 Ada Form Factor **20GB**

Full-Height Single Slot (4.4" Height x 9.5" Length)

Graphics Controller

Max Power: 130 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 16

Memory 20GB GDDR6

Memory Bandwidth: 360 GB/s

Memory Width: 256-bit

Connectors 4x DisplayPort 1.4a

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz

2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ 4500 Ada Form Factor **24GB**

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller

Max Power: 210 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 16

Memory 24GB GDDR6

Memory Bandwidth: 432 GB/s

Memory Width: 192-bit

Connectors

4x DisplayPort 1.4a

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz

2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:



Technical Specifications - Graphics

http://welcome.hp.com/country/us/en/support.html

NVIDIA®	RTX™	5000	Ada
22CP			

Form Factor

Full-Height Dual Slot (4.4" Height x 13.85" Length)

32**6**B

Graphics Controller

Max Power: 250 Watts

Cooling Solution: Active fan heatsink

Bus Type Memory

PCI Express 4.0 x 16 32GB GDDR6 with ECC

Memory Bandwidth: 576 GB/s

Memory Width: 256-bit

Connectors

4x DisplayPort 1.4a Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ 5880 Ada Form Factor

48GB

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller

Max Power: 285 Watts

PCI Express 4.0 x 16

Cooling Solution: Active fan heatsink

Bus Type Memory

48GB GDDR6 with ECC

Memory Bandwidth: 960 GB/s

Memory Width: 384-bit

Connectors

4x DisplayPort 1.4a Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Max simultaneous

4x 4096 x 2160 @ 120 Hz



Technical Specifications - Graphics

displays 4x 5120 x 2880 @ 60 Hz

2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ 6000 Ada Form Factor 48GB

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller

Max Power: 300 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 4.0 x 16 48GB GDDR6 with ECC Memory

Memory Bandwidth: 960 GB/s

Memory Width: 384-bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD Writer **Description** 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW
DVD+R DL
DVD-R DL
DVD-R
DVD-RW
CD-R
CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times Full Stroke DVD < 200 ms (seek)
Full Stroke CD < 200 ms (seek)

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X
DVD+R DL Up to 8X
DVD-R DL Up to 8X
DVD-ROM Up to 8X
DVD-ROM DL Up to 8X
DVD+R Up to 8X
DVD+R Up to 8X
DVD-R Up to 8X

Access Times Full Stroke DVD < 230 ms (typical)

Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity

10% to 80% 84° F (29° C)

Maximum Wet Bulb Temperature

Operating Systems Wir

Windows 10, Windows 11

Supported

Linux®



Technical Specifications - Optical and Removable Storage

Kit Contents HP SATA DVD Writer drive, installation guide.

Weight 0.35 lbs. (0.16 kg)

HP 9.5mm Slim DVD-ROM Description

Drive

9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA / ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times DVD-ROM Single Layer < 110 ms (typical)

CD-ROM Mode 1 < 110 ms (typical)
Full Stroke DVD < 230 ms (typical)
Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC – <800mA typical, < 1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity

Maximum Wet Bulb

10% to 80% 84° F (29° C)

Temperature

Operating Systems

Windows 10, Windows 11

Supported

Linux®

Kit Contents HP SATA DVD Writer drive, installation guide.



Technical Specifications - Networking and Communications

NETWORKING / COMMUNICATION

Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro™ with Intel® AMT 19.0) **Connector** RJ-45

Cabling Twisted pair up to 100m

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z

Bus Architecture PCI Express and SMBus

PCIe-based interface for active state operation (SO state) and SMBus for host and

Data Transfer Mode management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer

Mode

Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)

Network Transfer

Rate 10BASE-T (full-duplex) 20 Mbps

100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

10BASE-T (half-duplex) 10 Mbps

Management Capabilities

Notes

vPro, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI, Advanced

cable diagnostic, loopback modes,

AMT 19 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)

onboard LAN support RDP Wake on LAN function, if some networking device does

not support Modern standby feature for WOL limitation, suggest using this

Function for alternate solution for WOL G3-S5/S5/S4/MSC wake.

NOTE1: NDIS driver limitation and Wind11 OS, I219 switch to NDIS Driver and it only support IPV4 wake from MSC, if using IPV6 can't wake up from MSC. **NOTE2:** S4 can't wake up limitation on the NDIS Driver known issue.

HP 1-Port 1GbE Flex IO NIC

Connector RJ-45 (Single Port)

Cabling 1GbE over Category 5e (or better) up to 100m

Controller Realtek 8153 Ethernet Controller

Data Rates Supported 10/100/1000 Mbps

802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.1P Layer 2 Priority Encoding 802.3az (Energy

Compliance Efficient Ethernet)

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)



Technical Specifications - Networking and Communications

Boot ROM Support

Network Transfer

Mode

Full-duplex; Half-duplex

Yes

Network Transfer

Rate

1000BASE-T Full-Duplex 100BASE-TX Full-Duplex

100BASE-TX Half-Duplex 10BASE-T Full-Duplex 10BASE-T Half-Duplex 32° to 131° F (0° to 55° C)

Operating

Temperature

Dimensions (HxW)
Operating System

1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Driver Support

Windows 11 Windows 10 Linux®

HP 2.5GbE LAN Flex Port

Connector RJ-45 (Single Port)

Cabling Twisted Pair Cabling, up to 100 meters, 2.5GbE on CAT 5e UTP and up,

2.5Gbe/1GbE/10Mbps on CAT 5 UTP and up

Controller 1226

Data Rates Supported 10/100/1000Mbps and 2.5Gbps BASE-T

IEEE: 802.3 (Ethernet Interface for 2500BASE-T, 1000BASE-T, 100BASE-TX, and 10BASE-TE) 802.1AS-Rev 802.1Q (Virtual LAN) 802.1Qav 802.1Qbu 802.1Qbv 1588 802.1AS-REV 802.1p/Q 802.3br 802.3az (Energy Efficient Ethernet) 802.3x (Ethernet Flow Control) 802.3z CB Certification (International Safety) NRTL UL Certification (North America Safety) FCC Class B (USA) CE (European Union) ICES-003 Class B (Canada) BSMI (Taiwan) VCCI (Japan) KCC (Korea) CTICK (Australia/New

Compliance Zealand) UKCA (UK) UL (Safety) RoHS (Restricted or Hazardous Substances)

PCIe-based interface for active state operation (S0 state) and SMBus for host and

Bus Architecture management traffic (Sx and low power states)

Power Requirement Network Transfer

Mode

2.5W

Full-duplex; Half-duplex

2500BASE-T Full-Duplex 1000BASE-T Full-Duplex 100BASE-TX Full-Duplex 100BASE-TX Half-Duplex 10BASE-T Full-Duplex

Network Transfer

Rate

10BASE-T Full-Duplex 10BASE-T Half-Duplex

Operating System

Driver Support

Windows 11 Windows 10 Linux®



Technical Specifications - Networking and Communications

HP 10GBase-T Flex IO

Connector RJ-45 (Single Port)

10GbE over Category 6a (or better) up to 100m 5GbE over Category 5e (or

Cablingbetter) up to 100mControllerMarvell AQC113C

Data Rates Supported 10/100/1000 Mbps and 2.5/5/10 Gbps

v2 (Precision Clock Synchronization) NBASE-T™ Alliance PHY Specification CB Certification (International Safety) NRTL UL Certification (North America Safety) FCC Class B (USA) CE (European Union) ICES-003 Class B (Canada) BSMI (Taiwan) VCCI (Japan) KCC (Korea) CTICK (Australia/New Zealand) UKCA

802.3-2018 Clauses 55 and 126 802.3az (Energy Efficient Ethernet) 1588

Compliance (UK) UL (Safety) RoHS (Restricted or Hazardous Substances)

PCIe-based interface for active state operation (SO state) and SMBus for

Bus Architecture host and management traffic (Sx and low power states)

Power Requirement 6.5W

Network Transfer Mode Full-duplex; Half-duplex

10G BASE-T 5G BASE-T 2.5G BASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-T Te

Network Transfer Rate Operating System Driver

operating Syst

Support Notes Windows 11 Windows 10 Linux®

NOTE:1 Modern standby feature was not support & Suggest Customer use

Onboard Lan for Wake event instead of FLEX IO MSC Wake

The HP 10GBase-T Flex IO NIC can't support MSC (modern standby)/ S4/S5 wake, suggestion customer can use Onboard Lan RDP wake to replace the

MSC Wake instead of FLEX IO MSC Wake & Not support.

NOTE:2 Known issue with connection by FLEX IO module of LAN Cable, sometimes will auto resume in S4/S5 risk or User can manually disabled 10GBase-T FLOEX Wake function by changing the driver (Device Manager) this setting for "Wake from power off state" in Advanced.

HP Flex 1GbE Fiber LC Single Port

Connector1 LC Optical Fiber Port (Little Connector)CablingOptical Multi Mode Fiber OM2 or better

Controller AT-29M2/LC-AF-901

Data Rates Supported 1GbE

Compliance IEEE 802.3 IEEE 802.3u IEEE 802.3ab IEEE 802.1q VLAN Tagging IEEE 802.1AS



Technical Specifications - Networking and Communications

IEEE 1588

CB Certification (International Safety) NRTL UL Certification (North America Safety) FCC Class B (USA) CE (European Union) ICES-003 Class B (Canada) BSMI (Taiwan) VCCI (Japan) KCC (Korea) CTICK (Australia/New Zealand) UKCA (UK)

UL (Safety) RoHS (Restricted or Hazardous Substances)

Bus Architecture USB 3.1 interface, USB 2.0 interface,

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Power Requirement Up to 3W

Notes It's same locate at FLEX IO location and same as HP 2.5GbE LAN Flex Port and HP

10GBase-T Flex IO and HP 1-Port 1GbE Flex IO NIC

Z2 G1i Single 1Gbps Fiber NIC USB FLY YgritteF Adapter Connector1 LC Optical Fiber Port (Little Connector)CablingOptical Multi Mode Fiber OM2 or better

Controller AT-29M2/LC-AG-901

Data Rates Supported 1GbE

IEEE 802.3 IEEE 802.3u IEEE 802.3ab IEEE 802.1q VLAN Tagging IEEE 802.1AS

IEEE 1588 IEEE 802.3az Energy Efficient Ethernet

CB Certification (International Safety) NRTL UL Certification (North America Safety) FCC Class B (USA) CE (European Union) ICES-003 Class B (Canada) BSMI (Taiwan) VCCI (Japan) KCC (Korea) CTICK (Australia/New Zealand) UKCA (UK)

Compliance UL (Safety) RoHS (Restricted or Hazardous Substances)

Bus Architecture USB 3.1 interface, USB 2.0 interface,

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Power Requirement Up to 3W

Footnotes Rear IO of Single FLY USB Fiber Adapter, it's not located at FLEX IO location

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC **Connector** Dual-port SFP28

Cabling Transceiver with Multi-Mode Fiber (OM3 or OM4)

Controller ConnectX-6 Dx Network Transfer 1/10/25 GbE

Rates Supported

Data Path Width PCIe Gen4x8

Power Requirement 19.74W Maximum power available through SFP28 port: 2.5W (each port)

Operating 32° to 131° F (0° to 55° C)

Temperature

Dimensions (HxW) 6.22in. x 2.67in (158mm x 68mm)

Operating System Windows 11 64-Bit

Driver Linux®



Technical Specifications - Networking and Communications

*NVIDIA Mellanox ConnectX-6 SFP28 25GbE NIC with standard height bracket

attached

Low-profile bracketProduct Literature

Notes The NVIDIA® Mellanox® ConnectX-6 NIC can't support MSC (modern standby) / S4 /

S5 wake, suggestion customer can use Onboard Lan RDP wake to replace the MSC

Wake

HP 25GbE SFP28 LC Fiber Optic Transceiver

Connector LC Fiber Optic Connector

Cabling Typically, OM4 or higher MMF LC fiber optic cabling, up to 100m on OM4, up to 70m

on OM3

Data Rates Supported 25Gbps

Compliance SFF-8472 and 8431, Hot pluggable SFP+ footprint

Compatibility Intended for use with NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE NIC

Wavelength 850nm

Kit Contents 25GbE SFP28 Transceiver

HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver

Connector LC Fiber Optic Connector

Cabling Typically, OM4 or higher MMF LC fiber optic cabling, up to 300m on MMF

Data Rates Supported 10Gbps

Compliance SFF-8472 and 8431, Hot pluggable SFP+ footprint

Compatibility Intended for use with NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE NIC

Wavelength 850nm

Kit Contents 10GbE SFP+ Transceiver

Intel® X550-T2 2-Port 10GbE NIC **Connector** Dual-port RJ-45

Cabling Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m Intel® Ethernet Controller X550-AT2

Network Transfer

Metwork fram

Controller

Rates

Supported 10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE

Data Path WidthPCle Gen3x4Power Requirement3.9W at 100Mbps5.5W at 1Gbps

11.2W at 10Gbps

Operating

Temperature 32° to 131° F (0° to 55° C)



Technical Specifications - Networking and Communications

Dimensions (HxW) 167 mm x 69 mm Windows 11 64-Bit **Operating System** Driver Windows 10 64-bit

Linux®

Management DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP. **Capabilities** PXE 2.0 through boot ROM, Multi-mode I/O Virtualization, VxLAN, VMDq,

VLAN support with VLAN tag insertion

Kit Contents • Intel® X550-T2 2-Port 10GbE NIC with standard height bracket

attached

 Low-profile bracket • Product Literature

Notes The Intel® X550-T2 NIC can't support MSC (modern standby) / S4 / S5 wake,

suggestion customer can use Onboard Lan RDP wake to replace the MSC Wake

Allied Telesis AT2911T/2-901 Dual **Port 1GbE NIC**

Connector 2 x RJ-45 (Dual Port) Cabling Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Memory **Network Transfer**

17 Rx and 16 Tx queues 10/100/1000 Mbps

Rates Supported

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

> IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab

(10/100/1000T)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle 2x1

Data Transfer Mode PCIe-based interface **Power Requirement** 2.4 Watts (typical)

Management VLAN support, Link aggregation LACP, Link aggregation smart switch, **Capabilities** Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows

Management Instrumentation (WMI), PXE 2.1, SNMP

Kit Contents Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low-profile bracket

attached and standard bracket included

Notes The AT2911T/2-9 NIC can't support MSC (modern standby) wake, suggestion

customer can use Onboard Lan RDP wake to replace the MSC Wake

Intel® 1350-T4 4-Port **1GbE NIC**

Connector Cabling

4x RJ-45 (Quad Port) Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps



Technical Specifications - Networking and Communications

Cat5e (or higher) for 1Gbps up to 100m

Controller Intel® I350

Memory Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, Main Internal

memory is Error Code Correcting

Network Transfer

10Mbps, 100Mbps, 1Gbps

Rates Supported

Compliance IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3x, 802.3z,

IEEE1588 protocol and 802.1AS implementation, 802.3az EEE

Power Requirement 5W

Bus Architecture PCI Express 2.1 x4

Data Transfer Mode PCIe-based interface for active state operation

Network Transfer

multi-speed, full, and half-duplex

Mode

Network Transfer 10BASE-T Rate 100BASE-Tx 1000BASE-T

Management WOL, PXE 2.1, UEFI, Power Management Protocol Offload (proxying), MAC

Capabilities Power Management, Active State Power Management, VLAN, ACPI

Kit Contents Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height bracket installed

Low-profile bracket included

Notes The I350-T4 NIC can't support MSC (modern standby) /S4 wake, suggestion

customer can use Onboard Lan RDP wake to replace the MSC Wake

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2

WLAN Standards IEEE 802.11a, b, d, e, g, h, i, k, n, r, u, v, w, ac, ax; Fine Timing Measurement

based on 802.11-2016, 802.11az HW readiness

2x2 Dual-Band Antenna

Bluetooth Standards 5.3

Operating Temperature 32° to 122° F (0° to 50° C)

Interface M.2 CNVio2 **Dimensions** M.2 2230 **Kit Contents** Not Available

Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points is limited. Wi-Fi 6E is backward compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.



Technical Specifications - Networking and Communications

Intel[®] Wi-Fi 7 BE200 802.11be, BT 5.4, M.2 **WLAN Standards** IEEE 802.11a, b, d, e, g, h, i, k, n, r, u, v, w, ac, ax, be; Fine Timing

Measurement based on 802.11-2016, 802.11az HW readiness

Antenna 2x2 Dual-Band

Bluetooth Standards 5.4

Operating Temperature 32° to 122° F (0° to 50° C)

InterfaceM.2: PCIe, USBDimensionsM.2 2230Kit ContentsNot Available

Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE)

functionality requires Windows 11 24H2, select Intel® processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backward compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.



Date of change	Version History		Description of change
April 7, 2025	From v1 to v2	Changed	Social and Environmental Responsibility, Graphics sections
May 27, 2025	From v2 to v3	Changed	NETWORKING / COMMUNICATION section
June 1, 2025	From v3 to v4	Changed	Graphics section

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